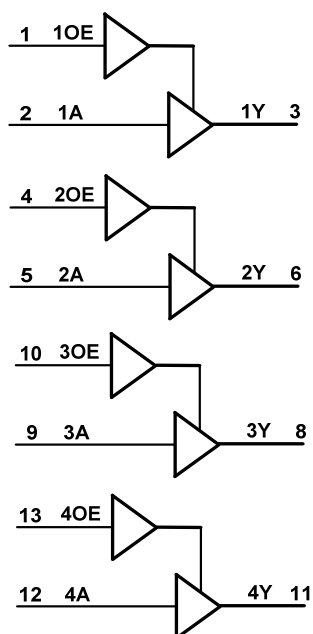


Pin Descriptions

Pin Number	Pin Name	Function
1	1OE	Data Enable Input (active low)
2	1A	Data Input
3	1Y	Data Output
4	2OE	Data Enable Input (active low)
5	2A	Data Input
6	2Y	Data Output
7	GND	Ground
8	3Y	Data Output
9	3A	Data Input
10	3OE	Data Enable Input (active low)
11	4Y	Data Outp
12	4A	Data Input
13	4OE	Data Enable Input (active low)
14	Vcc	Supply Voltage

Logic Diagram



Function Table

Inputs		Output
OE	A	Y
H	H	H
H	L	L
L	X	Z

Absolute Maximum Ratings (Note 4) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD CDM	Charged Device Model ESD Protection	1	KV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to +7.0	V
V _I	Input Voltage Range (Note 5)	-0.5 to +7.0	V
I _{IK}	Input Clamp Current V _I < -0.5V or V _I > V _{CC} +0.5V	±20	mA
I _{OK}	Output Clamp Current V _O < -0.5V or V _O > V _{CC} +0.5V	±20	mA
I _O	Continuous Output Current -0.5V < V _O < V _{CC} +0.5V	+/- 25	mA
I _{CC}	Continuous Current Through V _{CC}	50	mA
I _{GND}	Continuous Current Through GND	-50	mA
T _J	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C
P _{TOT}	Total Power Dissipation	500	mW

- Notes:
- Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.
 - Input Voltage cannot exceed V_{CC} to the extent the Maximum clamp current is exceeded.

Recommended Operating Conditions (Note 6) (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CC}	Supply Voltage		2.0	6.0	V
V _I	Input Voltage		0	V _{CC}	V
V _O	Output Voltage		0	V _{CC}	V
Δt/ΔV	Input Transition Rise or Fall Rate	V _{CC} = 2.0V		625	ns/V
		V _{CC} = 4.5V		140	
		V _{CC} = 6.0V		85	
T _A	Operating Free-Air Temperature		-40	+125	°C

- Note: 6. Unused inputs should be held at V_{CC} or ground.

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	V _{CC}	T _A = -40°C to +85°C		T _A = -40°C to +125°C		Unit
				Min	Max	Min	Max	
V _{IH}	High-level Input Voltage		2.0V	1.5		1.5		V
			4.5V	3.15		3.15		
			6.0V	4.2		4.2		
V _{IL}	Low-level input voltage		2.0V		0.5		0.5	V
			4.5V		1.35		1.35	
			6.0V		1.8		1.8	
V _{OH}	High-level Output Voltage	I _{OH} = -20μA	2.0V	1.9		1.9		V
		I _{OH} = -20μA	4.5V	4.4		4.4		
		I _{OH} = -20μA	6.0V	5.9		5.9		
		I _{OH} = -4.0mA	4.5V	3.84		3.7		
		I _{OH} = -5.2mA	6.0V	5.34		5.2		
V _{OL}	Low-level Output Voltage	I _{OL} = 20μA	2.0V		0.1		0.1	V
		I _{OL} = 20μA	4.5V		0.1		0.1	
		I _{OL} = 20μA	6.0V		0.1		0.1	
		I _{OL} = 4mA	4.5V		0.33		0.44	
		I _{OL} = 5.2mA	6.0V		0.33		0.44	
I _{OZ}	Z State Leakage Current	V _O = 0 to 6.0V V _I = GND or 6.0V	6.0V		± 5.0		± 10	μA
I _I	Input Current	V _I = GND to 5.5V	6.0V		± 1		± 1	μA
I _{CC}	Supply Current	V _I = GND or V _{CC} , I _O =0	6.0V		20		40	μA

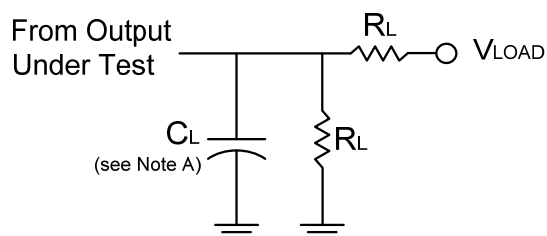
Switching Characteristics

Symbol	Parameter	Test Conditions	V _{CC}	T _A = +25°C			-40°C to +85°C	-40°C to +125°C	Unit
				Min	Typ	Max	Max	Max	
t _{PD}	Propagation Delay A _N to Y _N	Figure 1 C _L = 50pF	2.0V	—	30	100	125	150	ns
			4.5V	—	11	20	25	30	
			6.0V	—	9	17	21	26	
t _{EN}	Enable Time O _{EN} to Y _N	Figure 1 C _L = 50pF	2.0V	—	41	125	155	190	ns
			4.5V	—	15	25	31	38	
			6.0V	—	12	21	26	32	
t _{DIS}	Disable Time O _{EN} to Y _N	Figure 1 C _L = 50pF	2.0V	—	41	125	155	190	ns
			4.5V	—	15	25	31	38	
			6.0V	—	12	21	26	32	
t _t	Transition Time	Figure 1 C _L = 50pF	2.0V	—	14	60	75	90	ns
			4.5V	—	5	12	15	18	
			6.0V	—	4	10	13	15	

Operating Characteristics (@T_A = +25°C, unless otherwise specified.)

Parameter		Test Conditions	V _{CC} = 6V	Unit
			Typ	
C _{pd}	Power Dissipation Capacitance per Gate	f = 1 MHz	22	pF
C _I	Input Capacitance	V _I = V _{CC} – or GND	4	pF

Parameter Measurement Information



TEST	Condition
t_{PLZ} (see Notes D and E)	V_{load}
t_{PZL} (see Notes D and F)	V_{load}

V_{CC}	Inputs		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
2.0V to 6.0V	V_{CC}	$\leq 3ns$	$V_{CC}/2$	$2 \times V_{CC}$	15,50 pF	2 K Ω	10% of V_{CC}

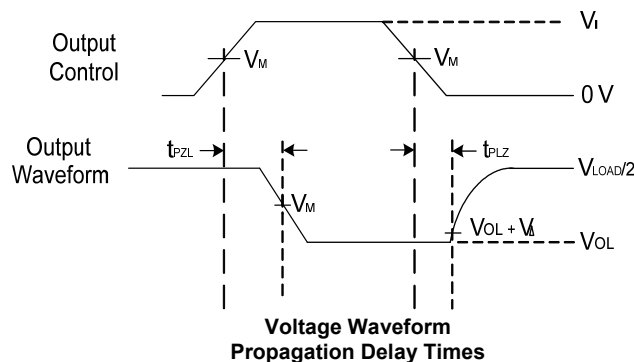
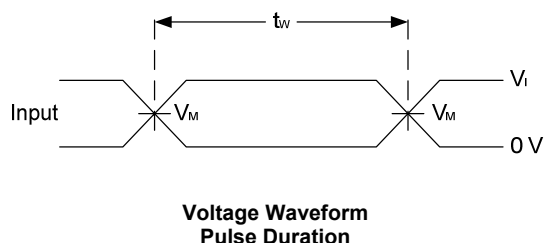
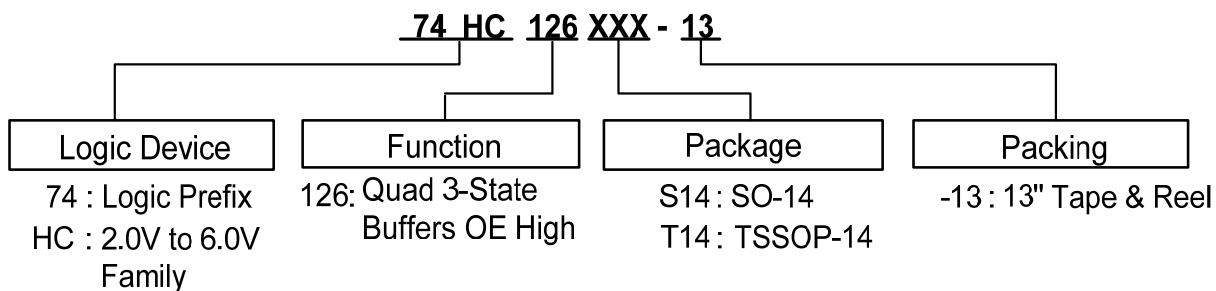


Figure 1 Load Circuit and Voltage Waveforms

- Notes:
- A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate ≤ 1 MHz
 - C. The inputs are measured one at a time with one transition per measurement.
 - D. For the 3 state device t_{PLZ} and t_{PZL} are the same as t_{PD} .
 - E. t_{PZL} is measured at V_M .
 - D. t_{PLZ} is measured at $V_{OL} + V_{\Delta}$

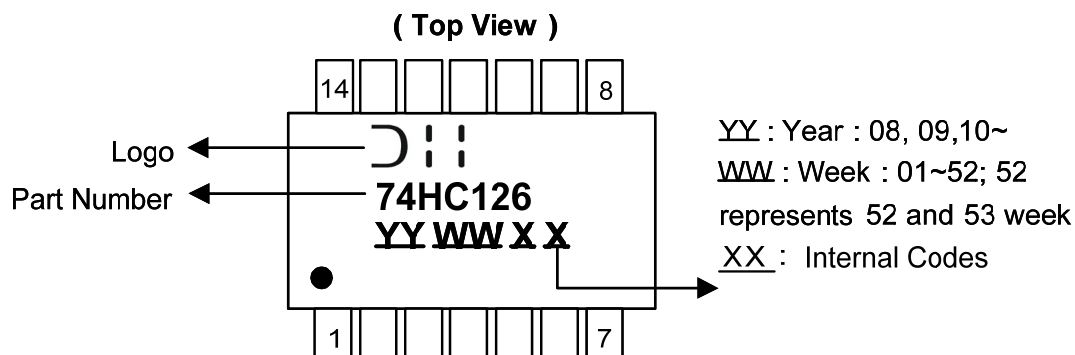
Ordering Information



Device	Package Code	Packaging	7" Tape and Reel	
			Quantity	Part Number Suffix
74HC126S14-13	S14	SO-14	2500/Tape & Reel	-13
74HC126T14-13	T14	TSSOP-14	2500/Tape & Reel	-13

Marking Information

(1) SO-14, TSSOP-14

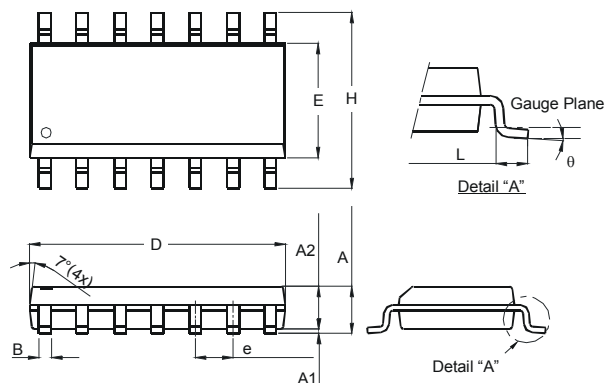


Part Number	Package
74HC126S14	SO-14
74HC126T14	TSSOP-14

Package Outline Dimensions (All dimensions in mm.)

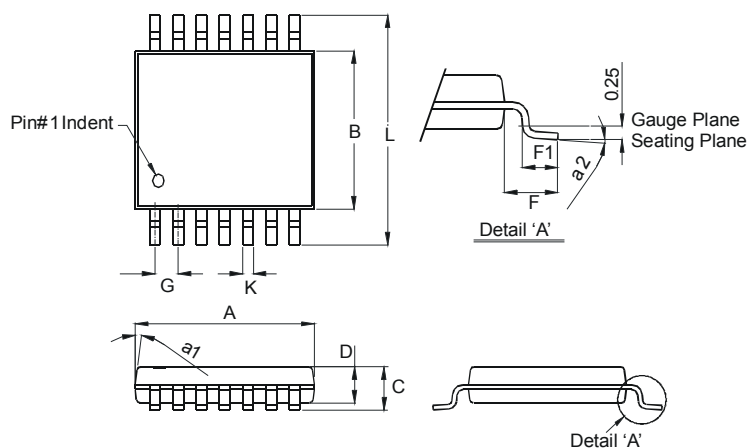
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.

Package Type: SO-14



SO-14		
Dim	Min	Max
A	1.47	1.73
A1	0.10	0.25
A2	1.45 Typ	
B	0.33	0.51
D	8.53	8.74
E	3.80	3.99
e	1.27 Typ	
H	5.80	6.20
L	0.38	1.27
θ	0°	8°
All Dimensions in mm		

Package Type: TSSOP-14

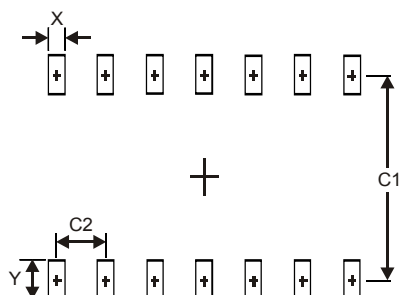


TSSOP-14		
Dim	Min	Max
a1	7° (4X)	
a2	0°	8°
A	4.9	5.10
B	4.30	4.50
C	—	1.2
D	0.8	1.05
F	1.00 Typ	
F1	0.45	0.75
G	0.65 Typ	
K	0.19	0.30
L	6.40 Typ	
All Dimensions in mm		

Suggested Pad Layout

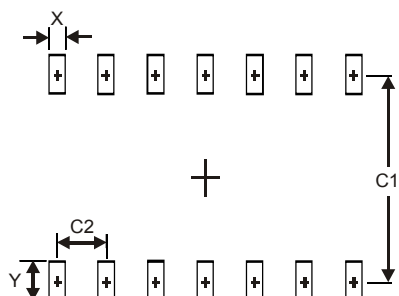
Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.

Package Type: SO-14



Dimensions	Value (in mm)
X	0.60
Y	1.50
C1	5.4
C2	1.27

Package Type: TSSOP-14



Dimensions	Value (in mm)
X	0.45
Y	1.45
C1	5.9
C2	0.65

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